

<b>Notice of References Cited</b>	Application/Control No. 10/767,658	Applicant(s)/Patent Under Reexamination OKAMOTO ET AL.	
	Examiner SHAMBHAVI PATEL	Art Unit 2128	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Sarval et al. 'Effective Modeling of the Reflow Soldering Process: Bases, Construction, and Operation of a Process Model'. IEEE Transactions on Component, Packaging, and Manufacturing Technology--Part C, Vol. 21, No. 2. April, 1998.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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